L Number	Hits	Search Text	DB	Time stamp
14	361	324/755.ccls. and (chip or die)	USPAT;	2002/10/22 12:27
			US-PGPUB;	}
			EPO; JPO;	
			DERWENT; IBM TDB	:
1.5	202	(224/755 gold and (chin or dia)) and	USPAT;	2002/10/22 13:03
15	292	(324/755.ccls. and (chip or die)) and (@ad<20000223)	US-PGPUB;	2002/10/22 13.03
		(ead 20000223)	EPO; JPO;	
Ì			DERWENT;	
			IBM TDB	la l
16	18	(324/755.ccls. and (chip or die)) and	USPĀT;	2002/10/22 12:38
		(conduct\$3 near elastomer)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		and distinguish (souther near alastomen)	IBM_TDB USPAT;	2002/10/22 13:31
17	29	conductive with (carbon near elastomer)	US-PGPUB;	2002/10/22 13.31
			EPO; JPO;	
ļ			DERWENT;	1
			IBM TDB	1
18	118	(conductive near elastomer) with (gold or	USPĀT;	2002/10/22 13:34
		nickel or silver or steel or au or ag or	US-PGPUB;	1
		ni)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	0000/10/00 10 51
19	49	((conductive near elastomer) with (gold or	USPAT;	2002/10/22 12:51
		nickel or silver or steel or au or ag or	US-PGPUB;	
		ni)) and (chip or die)	EPO; JPO; DERWENT;	
			IBM TDB	
21	65	((conductive near elastomer) with (carbon	USPAT;	2002/10/22 13:47
21	0.5	or gold or nickel or silver or steel or au	US-PGPUB;	2002, 10, 22 1011
		or ag or ni)) and (test or burn or kgd)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
22	53	(((conductive near elastomer) with (carbon	USPAT;	2002/10/22 13:16
		or gold or nickel or silver or steel or au	US-PGPUB;	
		or ag or ni)) and (test or burn or kgd))	EPO; JPO;	
		and (@ad<20000223)	DERWENT;	
	20	((conductive near elastomer) with (carbon	IBM_TDB USPAT;	2002/10/22 13:19
24	20	or gold or nickel or silver or steel or au		2002/10/22 13:13
		or ag or ni)) and 324/\$.ccls.	EPO; JPO;	1
		or ag or mr, and szr, r. corb.	DERWENT;	
	1 3 17		IBM TDB	1
25	2		USPAT;	2002/10/22 13:21
	1 10	or gold or nickel or silver or steel or au	US-PGPUB;	İ
		or ag or ni)) with (lid or cap or package)	EPO; JPO;	1
			DERWENT;	
26		((conductive near elastomer) with (carbon	IBM_TDB USPAT;	2002/10/22 13:21
26	2	or gold or nickel or silver or steel or au	US-PGPUB;	2002/10/22 13.21
	1	or ag or ni)) with (lid or cap or package	EPO; JPO;	
		or head)	DERWENT;	
		02	IBM TDB	
23	18		USPĀT;	2002/10/22 13:25
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	2002/10/22 12 20
20	240		USPAT;	2002/10/22 13:28
		or gold or nickel or silver or steel or au	US-PGPUB; EPO; JPO;	
		or ag or ni)	DERWENT;	
			IBM TDB	T.
27	2248	(variable adj resistance) and (test or	USPAT;	2002/10/22 13:30
-		burn or kgd)	US-PGPUB;	1
			EPO; JPO;	1
			DERWENT;	
			IBM TDB	1

28	519	((variable adj resistance) and (test or	USPAT;	2002/10/22 13:32
20	313	burn or kgd)) and (chip or die)	US-PGPUB;	
1		barn or nga,, and (oner to see,	EPO; JPO;	
	i		DERWENT;	
			IBM TDB	
29	70	((variable adj resistance) and (test or	USPAT;	2002/10/22 13:32
29	, 0	burn or kgd)) and elastomer	US-PGPUB;	
		Daili Ol kga// and olabeomel	EPO; JPO;	
			DERWENT;	
			IBM TDB	:
30	0	(chip or die) near((conductive near elastomer) with (gold or nickel or silver	USPAT;	2002/10/22 13:36
			US-PGPUB;	,, _, ,
		or steel or au or ag or ni))	EPO; JPO;	1
		or seed of an or ag or man	DERWENT;	:
			IBM TDB	t
31	6	(chip or die) with((conductive near	USPAT;	2002/10/22 13:46
		elastomer) with (gold or nickel or silver	US-PGPUB;	
		or steel or au or ag or ni))	EPO; JPO;	
			DERWENT;	
			IBM TDB	
32	38	((conductive near elastomer) with (carbon or gold or nickel or silver or steel or au	USPAT;	2002/10/22 13:41
1 32			US-PGPUB;	
		or ag or ni)) and package	EPO; JPO;	
		32 dg 02 32,, 333 [1]	DERWENT;	
			IBM TDB	
33	87	(chip or die) with (conductive near	USPAT;	2002/10/22 13:46
		elastomer)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
34	26	((chip or die) with (conductive near	USPAT;	2002/10/22 13:48
		elastomer)) and (test or burn or kgd)	US-PGPUB;	I
			EPO; JPO;	:
			DERWENT;	
			IBM_TDB	